

Material Declaration Report



Package Type:	TSOT23-6
Pericom Package Code:	TT06 (Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	12.063
Termination Plating:	Matte Tin
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	10-20
Tin Whisker Mitigation:	Anneal, 150C/1hr

MSL Rating:	1
Peak Body Temp (C):	260
Max Time (sec):	30
Reflow Cycles:	3
Rev Date:	Aug.03.2011

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	5.724	J	Epoxy Resin 1	Secret	5.00	0.28620
			Epoxy Resin 2	Secret	2.00	0.11448
			Phenol Resin	Secret	5.00	0.28620
			Carbon Black	1333-86-4	0.30	0.01717
			Silica	60676-86-0	85.00	4.86540
			Others	--	2.70	0.15455
LEAD FRAME	5.026		Cu	7440-50-8	99.30	4.99082
			Sn	7440-31-5	0.25	0.01257
			Zn	7440-66-6	0.20	0.01005
			Cr	7440-47-3	0.250	0.01257
			Silver	7440-22-4	--	--
TERMINATION PLATING	0.750		Tin	7440-31-5	99.90	0.74925
			Impurity	Proprietary	0.10	0.00075
SILICON DIE	0.350		Silicon	7440-21-3	99.763	0.34917
			Aluminum(Al)	7429-90-5	0.200	0.00070
			Copper(Cu)	7440-50-8	0.001	0.00000
			Titanium(Ti)	7440-32-6	0.028	0.00010
			Phosphorus(P)	7664-38-2	0.003	0.00001
			Boron(B)	7440-42-8	0.005	0.00002
DIE ATTACH EPOXY	0.038		Acrylic resin	Secret	30.00	0.01140
			Polybutadiene derivative	Secret	16.00	0.00608
			Butadiene Copolymer	Secret	2.00	0.00076
			Epoxy resin	Secret	4.00	0.00152
			Acrylate	Secret	24.00	0.00912
			Peroxide	Secret	5.00	0.00190
			Additive	Secret	5.00	0.00190
			Silica	68611-44-9	7.00	0.00266
			Boron compound	Secret	7.00	0.00266
GOLD WIRE	0.175		Au	7440-57-5	99.99	0.17498
			Other materials	Proprietary	0.01	0.00002

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Mold Compound	<2	<2	<2	<2	<5	<5
Leadframe	<50	<2	<2	<2	<5	<5
Device Silicon Die	<2	<2	<2	<2	<5	<5
Die Attach Epoxy	<2	<2	<2	<2	<5	<5
Gold Wire	<2	<2	<2	<2	<5	<5
Solder Plating	<2	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC and China RoHS Directive SJ/T11363-2006	Declaration Statement:	Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium					
		Pb	Hg	Cr+6	Cd	PBB	PBDE
	<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm	
	O	O	O	O	O	O	

O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.
X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.